

# SOT1951-1

FBGA1150, plastic, fine-pitch ball grid array package, 1150 balls, 0.65 mm pitch, 23 mm x 23 mm x 2.37 mm body

26 June 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	FBGA1150
<b>Package type industry code</b>	FBGA1150
<b>Package style descriptive code</b>	FBGA (fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	13-06-2019
<b>Manufacturer package code</b>	98ASA01135D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	23	-	mm
package width	-	23	-	mm
package height	-	2.37	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	1150	-	



2 Package outline

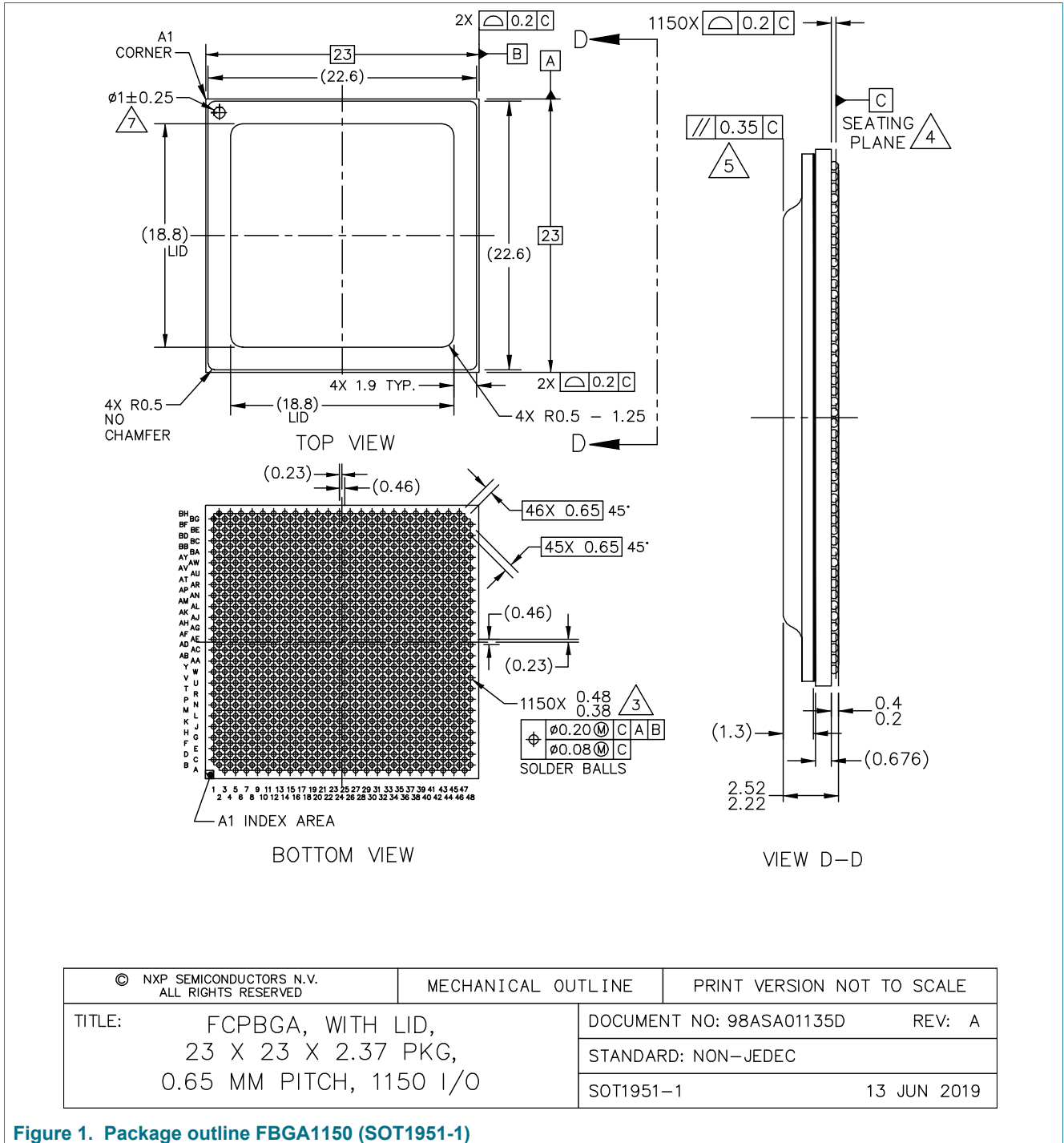


Figure 1. Package outline FBGA1150 (SOT1951-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN FOOT AREA.
8. LID OVERHANG ON THE SUBSTRATE IS NOT ALLOWED.

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TITLE: FCPBGA, WITH LID, 23 X 23 X 2.37 PKG, 0.65 MM PITCH, 1150 I/O		DOCUMENT NO: 98ASA01135D	REV: A
		STANDARD: NON-JEDEC	
		SOT1951-1	13 JUN 2019

Figure 2. Package outline note FBGA1150 (SOT1951-1)

### 3 Legal information

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